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DIMM Site Balance and Rework Procedure

Document Number and Revision: 923-7042626 Rev 5

Overview

This document provides a framework to any manufacturer who is requested to rework or repackage DIMMMs.

Audience

This document is for manufacturers of Oracle memory kits and for manufacturers who are requested to repackage and site balance DIMMs, as well as for Oracle Supplier Engineering.

The document is aimed at personnel who are trained in DIMM handling and final inspection of DIMMs.

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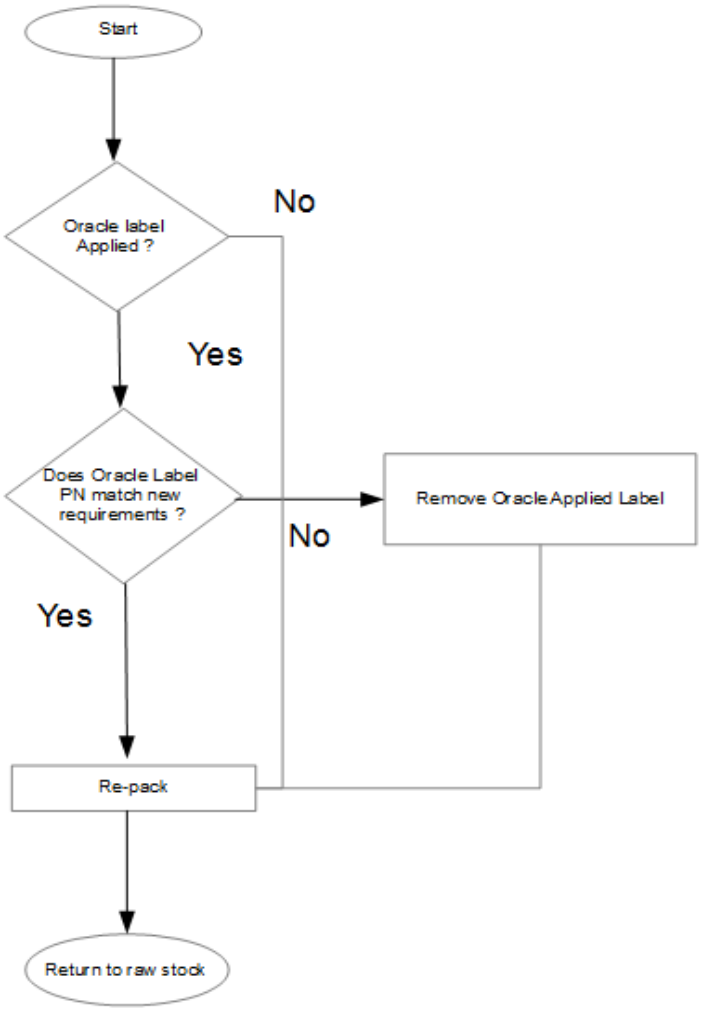
Introduction

The details outlined in this document are designed to offer guidance with site balancing and reworking DIMMs.

1 DIMM Site Balance Process Flow



2 DIMM Site Balance General Procedure

Perform the following:

1. Segregate the DIMMs by the supplier part number and pack them in the appropriate memory supplier trays.

NOTE 1: Use the correct type of tray for the DIMMs – the DDR3 DIMMs go in the DDR3 trays and the FBDIMMs go in the FBDIMM trays, and so on.

2. Apply a label to the outer tray, containing the following information:
    - DIMM supplier name: Micron, Samsung, and so on
    - Supplier part number: According to the supplier DIMM label
    - Tray quantity: Number of the DIMMs in the tray
3. Use an appropriate tape to seal the two adjacent sides of each tray.
4. Place the packed trays into an appropriate outer packing box.

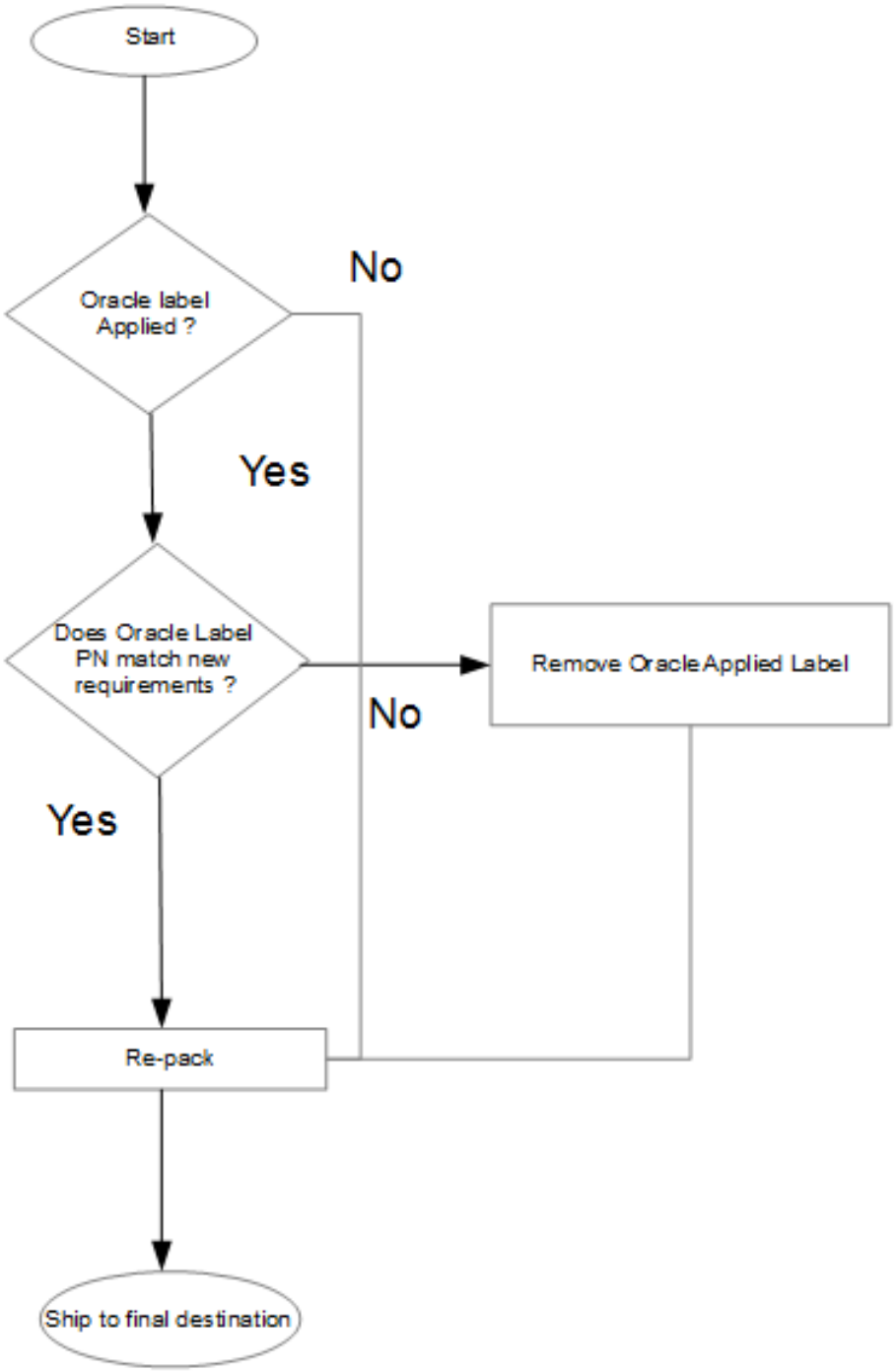
NOTE 2: The trays must be packed in a manner that minimizes the amount of movement within the outer packing box.

5. Tape the outer packing box according to the normal shipping rules or guidelines.
6. Label the outer packing box according to the Memory Commodity team's instructions.

2.1 DIMM Site Balance Hillsboro Guidelines

1. Where possible the Memory Commodity Team shall request site balancing based on fresh/raw DIMMs from specified locators.
2. In the event that fresh/raw stock is not available in the required quantities the Memory Commodity Team shall provide instructions on which locator should be used and the quantities required.
3. Reworking or label removal may be request on dekit material - Refer to rework process flow.
4. DIMM trays and outer boxes should be labeled as per standard practice unless specified otherwise by the Memory Commodity Team.

3 DIMM Rework Process Flow



4 DIMM Rework Procedure

Perform the following:

1. Relabel the DIMMs.

NOTE 3: DIMM relabeling must be performed in an ESD controlled environment and by personnel who are trained on DIMM handling and final visual inspection.

2. Check the details on the new label or lot against the work instructions.
   - If the new labels match the work instruction, proceed with relabeling.
   - If the new labels do not match the work instruction, return the DIMMs and contact an appropriate engineer or supervisor.
3. Place the rework tray to the left of the workbench and a new tray to the right for the relabeled DIMMs.

NOTE 4: The DIMMs must be placed flat down on an ESD workbench - their labels facing towards the operator.

4. Remove the label in accordance with document 7059302, *WWOPS Supplier Management and Product Lifecycle & Technology: DIMM Card and Socket Handling and Debug Requirements.*
5. Reapply a new label in accordance with document 7059302, *WWOPS Supplier Management and Product Lifecycle & Technology: DIMM Card and Socket Handling and Debug Requirements.*
6. Inspect the label content and legibility, as well as the DIMMs for signs of mechanical or handling damage.
7. Place the good relabeled DIMMs in the righthand tray and the defective DIMMs in a tray that is clearly marked as 'Containing defective DIMMs'.
8. Perform a DIMM count and label verification at the end of each lot.

NOTE 5: Failing DIMMs must be placed in a defective DIMMs tray that is clearly marked as 'Containing defective DIMMs'.

9. Record the results of the label and testing process and report any defective lots to Oracle along with the root cause of any defects.

Related Information

Document History

Rev	*Date*	*Description of Change*	*Originator*
01 A	14 Dec 2011	Initial release	N/A
Agile History			
02	20 Nov 2015	Updated Process flows (Sections 1 and 3) and Audience. Added Section 2.1, DIMM Site Balance Hillsboro Guidelines.	N/A
03	20 Mar 2016	Removed IPA cleaning step as the DIMMs will be relabeled in the area previously labeled (Section 4, previous steps 5 and 6).	N/A
Fusion History			
04	27 Oct 2016	Removed reference to 10% testing and Inspection Guidelines as well as altering the process flow diagrams. Changed the wording on Section 4 – DIMM Rework Procedure, points 4 and 5. It now points the user to document 7059302, WWOPS Supplier Management and Product Lifecycle & Technology: DIMM Card and Socket Handling and Debug Requirements.	N/A
05	04 May 2023	Update to Redwood format; no content change	N/A

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